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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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HD74LV2G00A

Dual 2–input NAND Gates



ADE-205-338B (Z)

Rev.2
Feb. 2003

Description

The HD74LV2G00A has dual two–input NAND gates in an 8 pin package. Low voltage and high speed operation is suitable for the battery powered products (e.g., notebook computers), and the low power consumption extends the battery life.

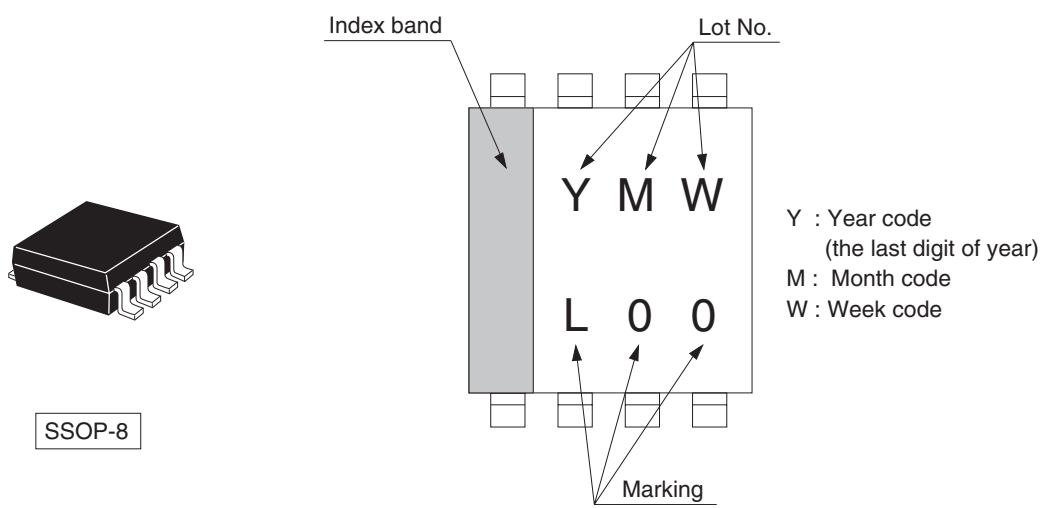
Features

- The basic gate function is lined up as hitachi uni logic series.
- Supplied on emboss taping for high speed automatic mounting.
- Electrical characteristics equivalent to the HD74LV00A
Supply voltage range : 1.65 to 5.5 V
Operating temperature range : –40 to +85°C
- All inputs V_{IH} (Max.) = 5.5 V (@ V_{CC} = 0 V to 5.5 V)
All outputs V_O (Max.) = 5.5 V (@ V_{CC} = 0 V)
- Output current ± 6 mA (@ V_{CC} = 3.0 V to 3.6 V), ± 12 mA (@ V_{CC} = 4.5 V to 5.5 V)
- All the logical input has hysteresis voltage for the slow transition.
- Ordering Information

Part Name	Package Type	Package Code	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LV2G00AUSE	SSOP-8 pin	TTP-8DBV	US	E (3,000 pcs/reel)

Outline and Article Indication

• HD74LV2G00A

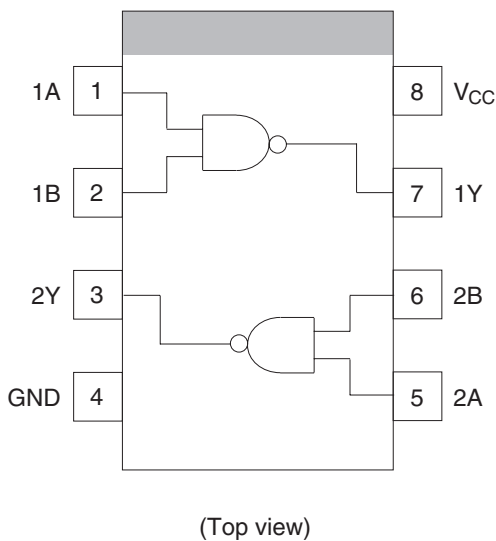


Function Table

Inputs		Output Y
A	B	
L	L	H
L	H	H
H	L	H
H	H	L

H : High level
L : Low level

Pin Arrangement



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit	Test Conditions
Supply voltage range	V_{CC}	-0.5 to 7.0	V	
Input voltage range ^{*1}	V_I	-0.5 to 7.0	V	
Output voltage range ^{*1,2}	V_O	-0.5 to $V_{CC} + 0.5$ -0.5 to 7.0	V	Output : H or L V_{CC} : OFF
Input clamp current	I_{IK}	-20	mA	$V_I < 0$
Output clamp current	I_{OK}	±50	mA	$V_O < 0$ or $V_O > V_{CC}$
Continuous output current	I_O	±25	mA	$V_O = 0$ to V_{CC}
Continuous current through V_{CC} or GND	I_{CC} or I_{GND}	±50	mA	
Maximum power dissipation at $T_a = 25^{\circ}\text{C}$ (in still air) ^{*3}	P_T	200	mW	
Storage temperature	T_{stg}	-65 to 150	°C	

- Notes:
- The absolute maximum ratings are values which must not individually be exceeded, and furthermore no two of which may be realized at the same time.
 - 1. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This value is limited to 5.5 V maximum.
 - 3. The maximum package power dissipation was calculated using a junction temperature of 150°C.

Recommended Operating Conditions

Item	Symbol	Min	Max	Unit	Conditions
Supply voltage range	V_{CC}	1.65	5.5	V	
Input voltage range	V_I	0	5.5	V	
Output voltage range	V_O	0	V_{CC}	V	
Output current	I_{OL}	—	1	mA	$V_{CC} = 1.65 \text{ to } 1.95 \text{ V}$
		—	2		$V_{CC} = 2.3 \text{ to } 2.7 \text{ V}$
		—	6		$V_{CC} = 3.0 \text{ to } 3.6 \text{ V}$
		—	12		$V_{CC} = 4.5 \text{ to } 5.5 \text{ V}$
	I_{OH}	—	−1		$V_{CC} = 1.65 \text{ to } 1.95 \text{ V}$
		—	−2		$V_{CC} = 2.3 \text{ to } 2.7 \text{ V}$
		—	−6		$V_{CC} = 3.0 \text{ to } 3.6 \text{ V}$
		—	−12		$V_{CC} = 4.5 \text{ to } 5.5 \text{ V}$
Input transition rise or fall rate	$\Delta t / \Delta v$	0	300	ns / V	$V_{CC} = 1.65 \text{ to } 1.95 \text{ V}$
		0	200		$V_{CC} = 2.3 \text{ to } 2.7 \text{ V}$
		0	100		$V_{CC} = 3.0 \text{ to } 3.6 \text{ V}$
		0	20		$V_{CC} = 4.5 \text{ to } 5.5 \text{ V}$
Operating free-air temperature	T_a	−40	85	°C	

Note: Unused or floating inputs must be held high or low.

Electrical Characteristic

- $T_a = -40$ to 85°C

Item	Symbol	V_{CC} (V) *	Min	Typ	Max	Unit	Test condition
Input voltage	V_{IH}	1.65 to 1.95	$V_{CC} \times 0.75$	—	—	V	
		2.3 to 2.7	$V_{CC} \times 0.7$	—	—		
		3.0 to 3.6	$V_{CC} \times 0.7$	—	—		
		4.5 to 5.5	$V_{CC} \times 0.7$	—	—		
	V_{IL}	1.65 to 1.95	—	—	$V_{CC} \times 0.25$		
		2.3 to 2.7	—	—	$V_{CC} \times 0.3$		
		3.0 to 3.6	—	—	$V_{CC} \times 0.3$		
		4.5 to 5.5	—	—	$V_{CC} \times 0.3$		
Hysteresis voltage	V_H	1.8	—	0.25	—	V	$V_T^+ - V_T^-$
		2.5	—	0.30	—		
		3.3	—	0.35	—		
		5.0	—	0.45	—		
Output voltage	V_{OH}	Min to Max	$V_{CC} - 0.1$	—	—	V	$I_{OH} = -50 \mu\text{A}$
		1.65	1.4	—	—		$I_{OH} = -1 \text{ mA}$
		2.3	2.0	—	—		$I_{OH} = -2 \text{ mA}$
		3.0	2.48	—	—		$I_{OH} = -6 \text{ mA}$
		4.5	3.8	—	—		$I_{OH} = -12 \text{ mA}$
	V_{OL}	Min to Max	—	—	0.1		$I_{OL} = 50 \mu\text{A}$
		1.65	—	—	0.3		$I_{OL} = 1 \text{ mA}$
		2.3	—	—	0.4		$I_{OL} = 2 \text{ mA}$
		3.0	—	—	0.44		$I_{OL} = 6 \text{ mA}$
		4.5	—	—	0.55		$I_{OL} = 12 \text{ mA}$
Input current	I_{IN}	0 to 5.5	—	—	± 1	μA	$V_{IN} = 5.5 \text{ V}$ or GND
Quiescent supply current	I_{CC}	5.5	—	—	10	μA	$V_{IN} = V_{CC}$ or GND, $I_O = 0$
Output leakage current	I_{OFF}	0	—	—	5	μA	V_{IN} or $V_O = 0$ to 5.5 V
Input capacitance	C_{IN}	3.3	—	2.5	—	pF	$V_{IN} = V_{CC}$ or GND

Note: For conditions shown as Min or Max, use the appropriate values under recommended operating conditions.

Switching Characteristics

- $V_{CC} = 1.8 \pm 0.15 \text{ V}$

Item	Symbol	$T_a = 25^\circ\text{C}$			$T_a = -40 \text{ to } 85^\circ\text{C}$		Unit	Test Conditions	FROM (Input)	TO (Output)
		Min	Typ	Max	Min	Max				
Propagation delay time	t_{PLH}	—	12.7	23.1	1.0	25.5	ns	$C_L = 15 \text{ pF}$	A or B	Y
	t_{PHL}	—	18.7	33.4	1.0	37.0		$C_L = 50 \text{ pF}$		

- $V_{CC} = 2.5 \pm 0.2 \text{ V}$

Item	Symbol	$T_a = 25^\circ\text{C}$			$T_a = -40 \text{ to } 85^\circ\text{C}$		Unit	Test Conditions	FROM (Input)	TO (Output)
		Min	Typ	Max	Min	Max				
Propagation delay time	t_{PLH}	—	7.1	12.9	1.0	15.0	ns	$C_L = 15 \text{ pF}$	A or B	Y
	t_{PHL}	—	9.6	16.6	1.0	20.0		$C_L = 50 \text{ pF}$		

- $V_{CC} = 3.3 \pm 0.3 \text{ V}$

Item	Symbol	$T_a = 25^\circ\text{C}$			$T_a = -40 \text{ to } 85^\circ\text{C}$		Unit	Test Conditions	FROM (Input)	TO (Output)
		Min	Typ	Max	Min	Max				
Propagation delay time	t_{PLH}	—	5.0	7.9	1.0	9.5	ns	$C_L = 15 \text{ pF}$	A or B	Y
	t_{PHL}	—	6.9	11.4	1.0	13.0		$C_L = 50 \text{ pF}$		

- $V_{CC} = 5.0 \pm 0.5 \text{ V}$

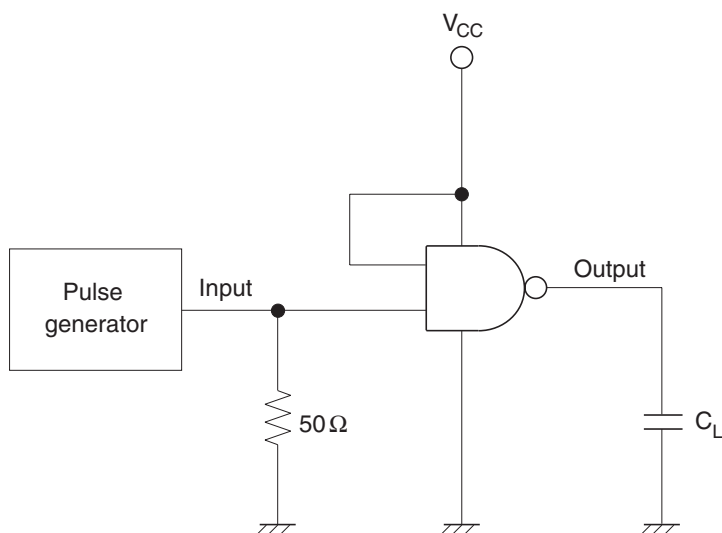
Item	Symbol	$T_a = 25^\circ\text{C}$			$T_a = -40 \text{ to } 85^\circ\text{C}$		Unit	Test Conditions	FROM (Input)	TO (Output)
		Min	Typ	Max	Min	Max				
Propagation delay time	t_{PLH}	—	3.6	5.5	1.0	6.5	ns	$C_L = 15 \text{ pF}$	A or B	Y
	t_{PHL}	—	4.9	7.5	1.0	8.5		$C_L = 50 \text{ pF}$		

Operating Characteristics

- $C_L = 50 \text{ pF}$

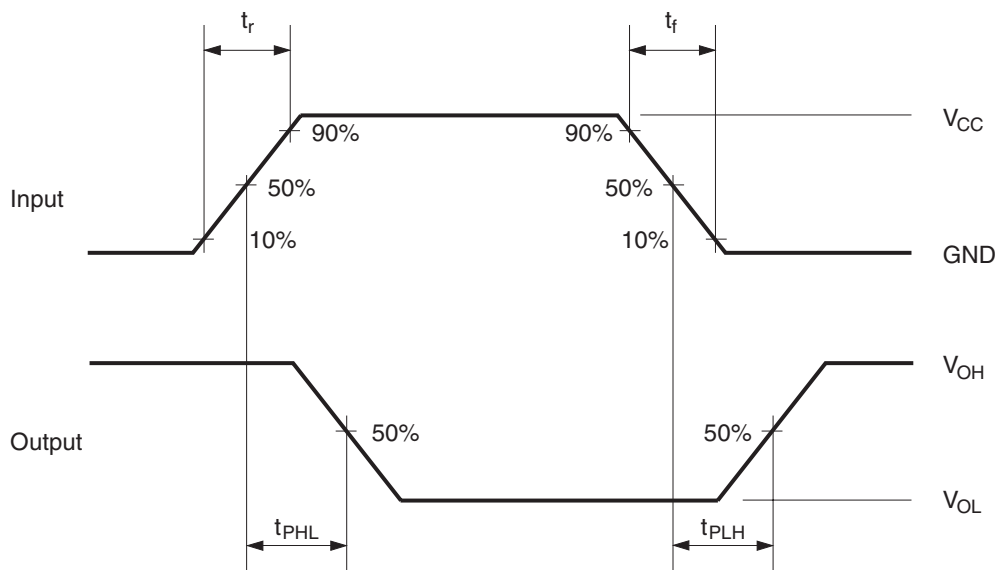
Item	Symbol	$V_{CC} \text{ (V)}$	$T_a = 25^\circ\text{C}$			Unit	Test Conditions
			Min	Typ	Max		
Power dissipation	C_{PD}	3.3	—	9.5	—	pF	$f = 10 \text{ MHz}$
capacitance		5.0	—	11.0	—		

Test Circuit



Note: 1. C_L includes probe and jig capacitance.

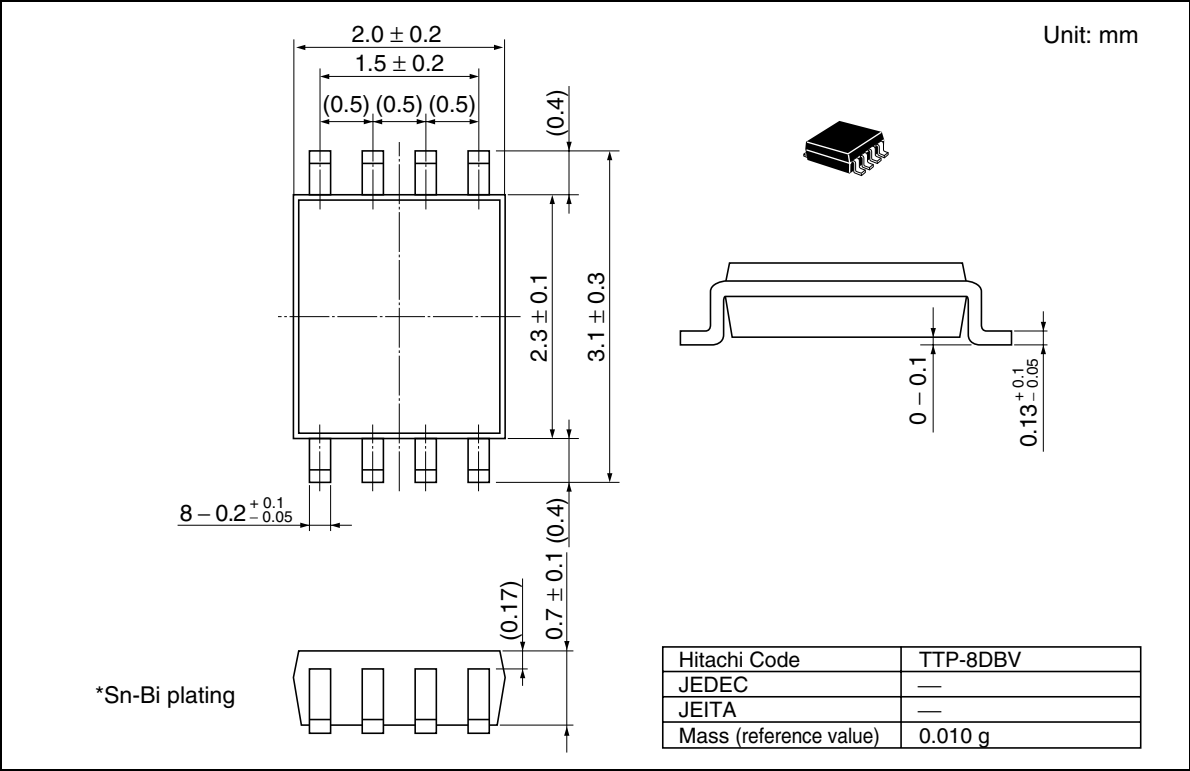
• Waveforms



Notes: 1. Input waveform : $PRR \leq 1 \text{ MHz}$, $Z_o = 50 \Omega$, $t_r \leq 3 \text{ ns}$, $t_f \leq 3 \text{ ns}$.

2. The output are measured one at a time with one transition per measurement.

Package Dimensions



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